



Material Content Data Sheet



Sales Product Name	TLE7235SE			Issued		8. October 2014		
MA#	MA000774048							
Package	PG-DSO-20-45			Weight*		588.73 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.437	1.26	1.26	12633	12633
leadframe	inorganic material	phosphorus	7723-14-0	0.047	0.01		81	
	non noble metal	zinc	7440-66-6	0.190	0.03		322	
	non noble metal	iron	7439-89-6	3.797	0.64		6450	
	non noble metal	copper	7440-50-8	154.185	26.19	26.87	261893	268746
wire	noble metal	gold	7440-57-5	0.858	0.15	0.15	1458	1458
encapsulation	organic material	carbon black	1333-86-4	0.828	0.14		1407	
	plastics	epoxy resin	-	38.107	6.47		64727	
	inorganic material	silicondioxide	60676-86-0	375.269	63.74	70.35	637416	703550
leadfinish	non noble metal	tin	7440-31-5	4.487	0.76	0.76	7621	7621
plating	noble metal	silver	7440-22-4	0.800	0.14	0.14	1359	1359
glue	plastics	epoxy resin	-	0.682	0.12		1158	
	noble metal	silver	7440-22-4	2.046	0.35	0.47	3475	4633
*deviation	< 10%	Sum in total:			100.00			1000000

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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